



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC047N08NS3 G		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001247748					
<b>Package</b>				PG-TDSON-8-1		<b>Weight*</b>		122.20 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.414	3.61	3.61	36121	36121	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	309016	309418	
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	533	533	
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		653		
	plastics	epoxy resin	-	5.661	4.63		46330		
	inorganic material	silicondioxide	60676-86-0	34.128	27.93	32.63	279284	326267	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1355	1355	
solder	noble metal	silver	7440-22-4	0.087	0.07		712		
	non noble metal	tin	7440-31-5	0.070	0.06		569		
	non noble metal	lead	7439-92-1	3.322	2.72	2.85	27181	28462	
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10552	10552	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92635	92756	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	copper	7440-50-8	22.292	18.24	18.27	182419	182657	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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